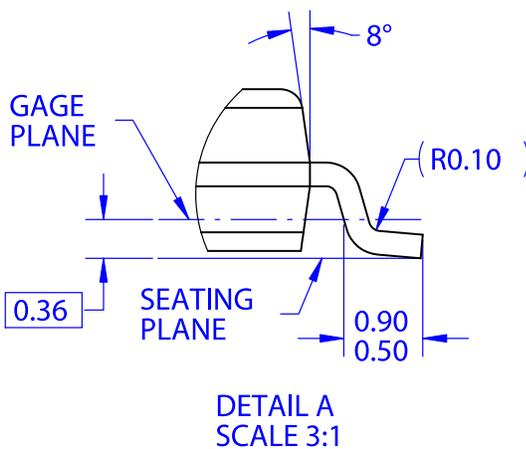
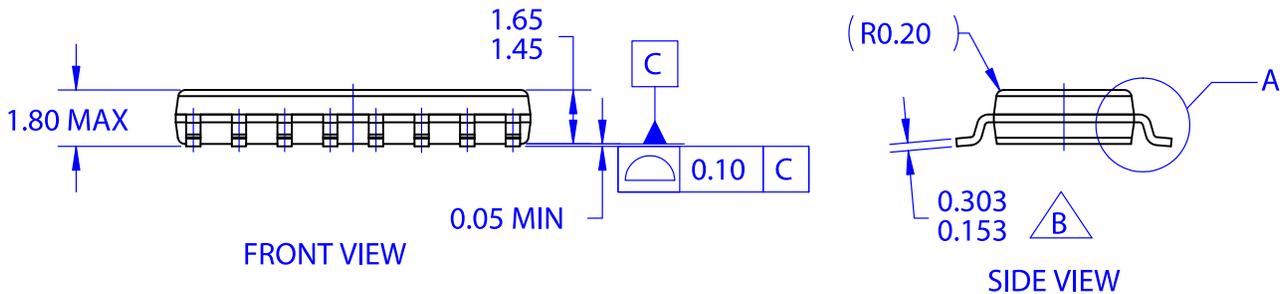
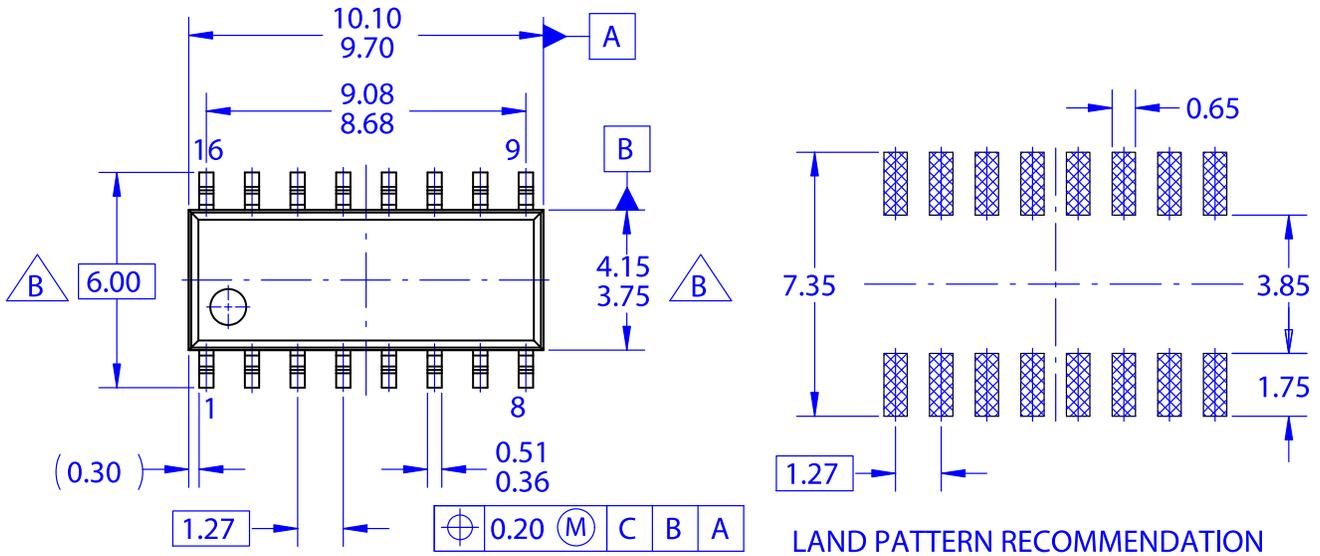


**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

**SOIC16 N**  
CASE 751ES  
ISSUE O

DATE 31 DEC 2016



- NOTES:**
- A. THIS DRAWING COMPLIES WITH JEDEC MS-012, EXCEPT AS NOTED
  - B. THIS DIMENSION IS OUTSIDE JEDEC MS-012 VALUE
  - C. ALL DIMENSIONS ARE IN MILLIMETERS
  - D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS

|                         |                    |  |
|-------------------------|--------------------|--|
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| <b>DESCRIPTION:</b>     | <b>SOIC16 N</b>    | <b>PAGE 1 OF 1</b>   |

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